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(54) **HIGH ELECTRON MOBILITY TRANSISTOR AND METHOD OF FORMING THE SAME**

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CPC ..... **H01L 29/7787** (2013.01); **H01L 21/0254** (2013.01); **H01L 21/0262** (2013.01); **H01L 21/7685** (2013.01); **H01L 29/201** (2013.01); **H01L 29/2003** (2013.01); **H01L 29/205** (2013.01); **H01L 29/4232** (2013.01); **H01L 29/42372** (2013.01); **H01L 29/66431** (2013.01); **H01L 29/66462** (2013.01); **H01L 29/778** (2013.01); **H01L 29/7783** (2013.01)

(58) **Field of Classification Search**

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USPC ..... 257/76, 192, 200, E29.091; 438/197  
See application file for complete search history.

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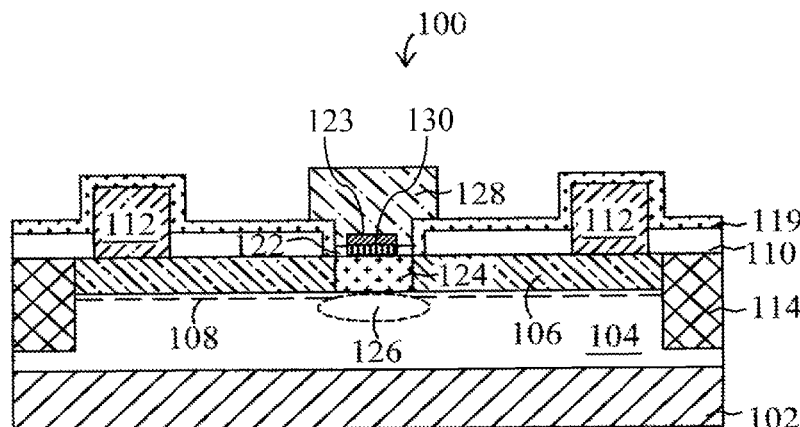
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(57) **ABSTRACT**

A semiconductor structure includes a first III-V compound layer. A second III-V compound layer is disposed on the first III-V compound layer and is different from the first III-V compound layer in composition. A carrier channel is located between the first III-V compound layer and the second III-V compound layer. A source feature and a drain feature are disposed on the second III-V compound layer. A gate electrode is disposed over the second III-V compound layer between the source feature and the drain feature. A fluorine region is embedded in the second III-V compound layer under the gate electrode. A diffusion barrier layer is disposed on top of the second III-V compound layer. A gate dielectric layer is disposed over the second III-V compound layer. The gate dielectric layer has a fluorine segment on the fluorine region and under at least a portion of the gate electrode.

**20 Claims, 4 Drawing Sheets**



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|      | <b>H01L 29/201</b> | (2006.01) |                   |        |                       |         |
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Fig. 2

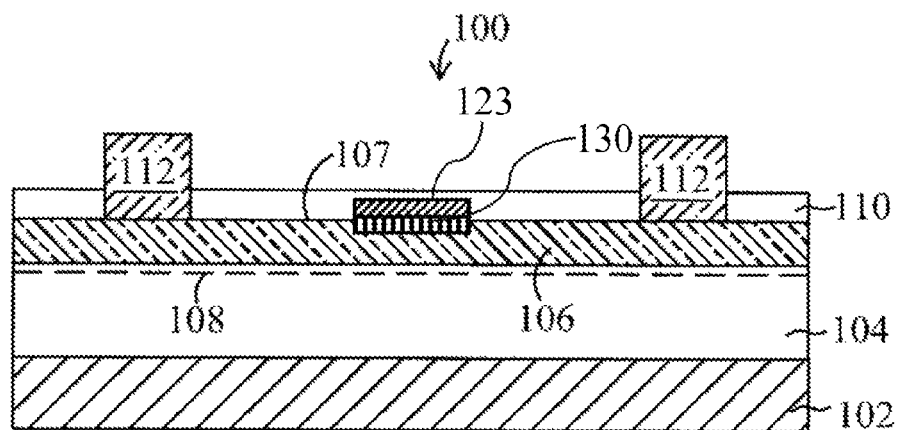


Fig. 3

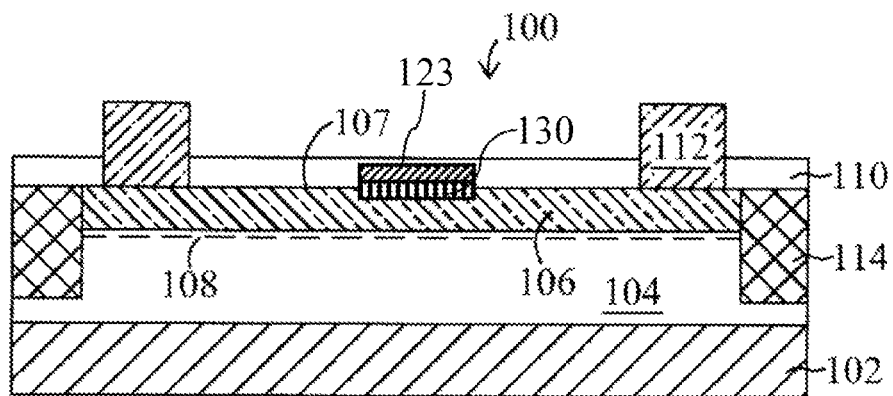


Fig. 4

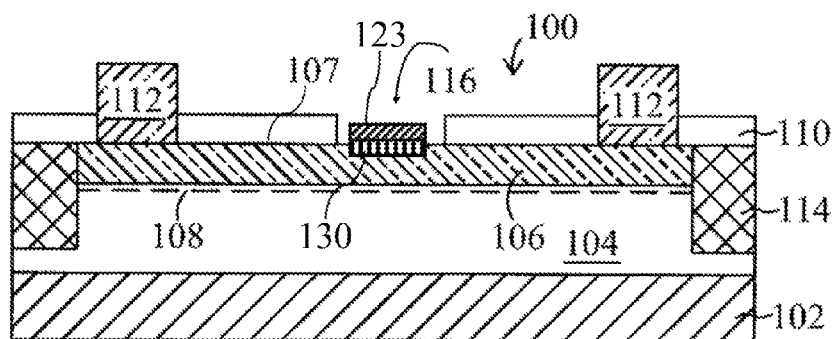


Fig. 5

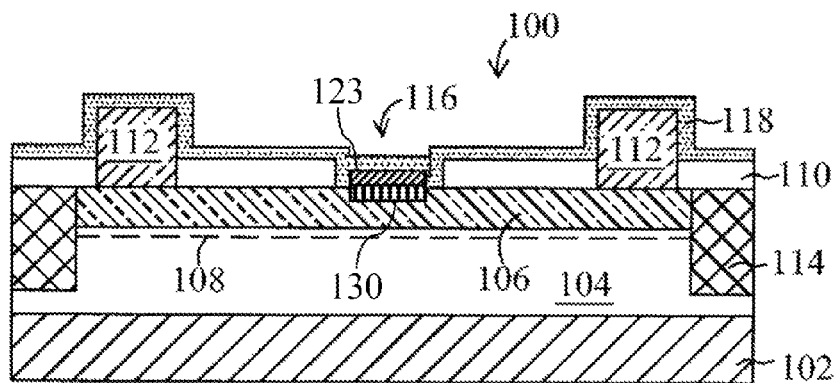


Fig. 6

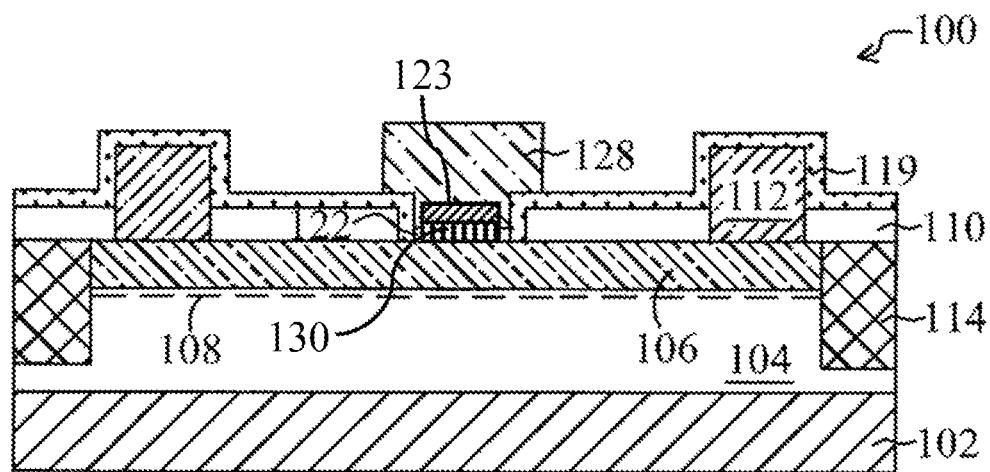


Fig. 7

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# HIGH ELECTRON MOBILITY TRANSISTOR AND METHOD OF FORMING THE SAME

## PRIORITY CLAIM AND CROSS-REFERENCE

The present application is a continuation of U.S. application Ser. No. 13/774,614, entitled "High Electron Mobility Transistor and Method of Forming the Same," filed on Feb. 22, 2013, which is incorporated herein by reference.

## TECHNICAL FIELD

This disclosure relates generally to a semiconductor structure and, more particularly, to a high electron mobility transistor (HEMT) and method for forming a high electron mobility transistor.

## BACKGROUND

In semiconductor technology, due to their characteristics, Group III-Group V (or III-V) semiconductor compounds are used to form various integrated circuit devices, such as high power field-effect transistors, high frequency transistors, or high electron mobility transistors (HEMTs). A HEMT is a field effect transistor incorporating a junction between two materials with different band gaps (i.e., a heterojunction) as the channel instead of a doped region, as is generally the case for metal oxide semiconductor field effect transistors (MOSFETs). In contrast with MOSFETs, HEMTs have a number of attractive properties including high electron mobility, the ability to transmit signals at high frequencies, etc.

From an application point of view, enhancement-mode (E-mode) HEMTs have many advantages. E-mode HEMTs allow elimination of negative-polarity voltage supply, and, therefore, reduction of the circuit complexity and cost. Despite the attractive properties noted above, a number of challenges exist in connection with developing III-V semiconductor compound-based devices. Various techniques directed at configurations and materials of these III-V semiconductor compounds have been implemented to try and further improve transistor device performance.

Frequently, layers of a semiconductor are doped in the manufacturing process. Magnesium (Mg) is a common dopant for a P-type gallium nitride (p-GaN). Mg always diffuses into active layers and impacts performance, specifically in the 2-dimensional electron gas (2DEG) and current density of HEMT devices.

## BRIEF DESCRIPTION OF THE DRAWINGS

Aspects of the present disclosure may be understood from the following detailed description and the accompanying figures. It is emphasized that, in accordance with the standard practice in the industry, various features are not drawn to scale. In fact, the dimensions of the various features may be arbitrarily increased or reduced for clarity of discussion.

FIG. 1 is a cross-sectional view of a semiconductor structure having a high electron mobility transistor (HEMT) according to one or more embodiments of this disclosure.

FIG. 2 is a flowchart of a method of forming a semiconductor structure having a HEMT according to one or more embodiments of this disclosure.

FIGS. 3 to 7 are cross-sectional views of a semiconductor structure having a HEMT at various stages of manufacture according to one embodiment of the method of FIG. 2.

## DETAILED DESCRIPTION

The making and using of illustrative embodiments are discussed in detail below. It should be appreciated, however, that

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the disclosure provides many applicable inventive concepts that can be embodied in a wide variety of specific contexts. The specific embodiments discussed are merely illustrative and do not limit the scope of the disclosure.

A plurality of semiconductor chip regions is marked on the substrate by scribe lines between the chip regions. The substrate will go through a variety of cleaning, layering, patterning, etching and doping steps to form integrated circuits. The term "substrate" herein generally refers to the bulk substrate on which various layers and device structures are formed. In some embodiments, the bulk substrate includes silicon or a compound semiconductor, such as GaAs, InP, SiGe, or SiC. Examples of such layers include dielectric layers, doped layers, polysilicon layers, diffusion barrier layers, or conductive layers. Examples of device structures include transistors, resistors, and/or capacitors, which may be interconnected through an interconnect layer to additional integrated circuits.

FIG. 1 is a cross-sectional view of a semiconductor structure 100 having a high electron mobility transistor (HEMT) and an InGaN diffusion barrier layer 130 according to one or more embodiments of this disclosure.

Referring to FIG. 1, the semiconductor structure 100 having a HEMT is illustrated. The semiconductor structure 100 includes a substrate 102. In some embodiments, the substrate 102 includes a silicon carbide (SiC) substrate, sapphire substrate or a silicon substrate.

The semiconductor structure 100 also includes a heterojunction formed between two different semiconductor material layers, such as material layers with different band gaps. For example, the semiconductor structure 100 includes a non-doped narrow-band gap channel layer and a wide-band gap n-type donor-supply layer. In at least one embodiment, the semiconductor structure 100 includes a first III-V compound layer (or referred to as a channel layer) 104 formed on the substrate 102 and a second III-V compound layer (or referred to as a donor-supply layer) 106 formed on the channel layer 104. The channel layer 104 and the donor-supply layer 106 are compounds made from the III-V groups in the periodic table of elements. However, the channel layer 104 and the donor-supply layer 106 are different from each other in composition. The channel layer 104 is undoped or unintentionally doped (UID). In the present example of the semiconductor structure 100, the channel layer 104 includes a gallium nitride (GaN) layer (also referred to as the GaN layer 104). The donor-supply layer 106 includes an aluminum gallium nitride (AlGaIn) layer (also referred to as AlGaIn layer 106). The GaN layer 104 and AlGaIn layer 106 directly contact each other. In another example, the channel layer 104 includes a GaAs layer or InP layer. The donor-supply layer 106 includes an AlGaAs layer or an AlInP layer.

The GaN layer 104 is undoped. Alternatively, the GaN layer 104 is unintentionally doped, such as lightly doped with n-type dopants due to a precursor used to form the GaN layer 104. In one example, the GaN layer 104 has a thickness in a range from about 0.5 microns to about 10 microns.

The AlGaIn layer 106 is unintentionally doped. In one example, the AlGaIn layer 106 has a thickness in a range from about 5 nanometers (nm) to about 50 nm.

The InGaIn diffusion barrier layer 130 may prevent the degradation of the HEMT device. The direction of the polarization-induced field formed in the InGaIn is opposite to that in AlGaIn thereby lifting the conduction band in the InGaIn capped HEMTs. This design may decrease the 2DEG channel density and may create a positive  $V_{th}$  when compared to conventional AlGaIn/GaN HEMTs.

The band gap discontinuity exists between the AlGaIn layer 106 and the GaN layer 104. The electrons from a piezo-

electric effect in the AlGaIn layer **106** drop into the GaN layer **104**, creating a very thin layer **108** of highly mobile conducting electrons in the GaN layer **104**. This thin layer **108** is referred to as a two-dimensional electron gas (2DEG), forming a carrier channel (also referred to as the carrier channel **108**). The thin layer **108** of 2DEG is located at an interface of the AlGaIn layer **106** and the GaN layer **104**. Thus, the carrier channel has high electron mobility because the GaN layer **104** is undoped or unintentionally doped, and the electrons can move freely without collision or with substantially reduced collisions with impurities.

The semiconductor structure **100** may also include an InGaIn diffusion barrier layer **130** disposed between an AlGaIn layer and a p-GaN layer. The InGaIn diffusion barrier layer **130** may prevent diffusion into the HEMT active layer because the diffusion coefficient of Mg in InGaIn is lower than in AlGaIn. In one example, the InGaIn diffusion barrier layer **130** has a thickness in a range from about 3 nm to about 15 nm.

The semiconductor structure **100** also includes a source feature and a drain feature disposed on the AlGaIn layer **106** and configured to electrically connect to the carrier channel **108**. Each of the source feature and the drain feature comprises a metal feature **112**. In one example, the metal feature **112** is free of Au and comprises Al, Ti, or Cu.

The semiconductor structure **100** further includes a dielectric cap layer **110** disposed on a top surface of the AlGaIn layer **106** not occupied by the metal features **112**. The dielectric cap layer **110** further includes an opening that exposes a portion of the AlGaIn layer **106** for a gate electrode formation, and a P-type GaN structure **123**. The width of the opening in the dielectric cap layer **110** is greater than the width of the P-type GaN structure **123**. The dielectric cap layer **110** protects the underlying AlGaIn layer **106** from damage in the following process having plasma.

The semiconductor structure **100** further includes isolation regions **114** in the first III-V compound layer **104** and the second III-V compound layer **106**. The isolation regions **114** isolate the HEMT in the structure **100** from other devices in the substrate **102**. In one example, the isolation region **114** includes a doped region with species of oxygen or nitrogen.

The semiconductor structure **100** further includes a gate dielectric layer **119** deposited on the dielectric cap layer **110** and top surfaces of the source feature and the drain feature. The gate dielectric layer **119** is also disposed along an interior surface of the opening and on the exposed portion of the AlGaIn layer **106**. In one example, the gate dielectric layer **119** has a thickness in a range from about 3 nm to about 20 nm. In some examples, the gate dielectric layer **119** comprises silicon oxide, silicon nitride, gallium oxide, aluminum oxide, scandium oxide, zirconium oxide, lanthanum oxide or hafnium oxide.

In some embodiments, the semiconductor structure **100** further includes a protection layer (not shown). The protection layer is disposed on top surfaces of the metal features **112** and under the gate dielectric layer **119**. The protection layer further includes an opening that aligns with the opening in the dielectric cap layer **110**. The combined opening of the opening in the protection layer and the opening in the dielectric cap layer **110** exposes the portion of the AlGaIn layer **106** and a P-type GaN structure **123** for the gate electrode formation. The protection layer also covers the source feature and the drain feature, and prevents the source feature and the drain feature from exposure during an annealing process in the formation of the isolation regions **116**.

The semiconductor structure **100** also includes a gate electrode **128** disposed on the opening over AlGaIn layer **106**

between the source and drain features. The gate electrode **128** includes a conductive material layer configured for voltage bias and electrical coupling with the carrier channel **108**. In various examples, the conductive material layer includes a refractory metal or its compounds, e.g., titanium (Ti), titanium nitride (TiN), titanium tungsten (TiW) and tungsten (W). In another example, the conductive material layer includes nickel (Ni), gold (Au) or copper (Cu).

The semiconductor structure **100** also includes a depletion region **126** in the carrier channel **108** under the opening in the dielectric cap layer **110**. The carrier channel **108** becomes normally-off because of the depletion region **126**. A positive gate voltage should be applied to turn on the carrier channel **108** of this HEMT. This HMET is also called an enhanced-mode HEMT that is opposite to a depletion-mode HEMT. The depletion-mode HEMT has a normally-on carrier channel and a negative gate voltage should be applied to turn off the carrier channel.

In the above described embodiments, the gate electrode **128**, the source/drain features, and the carrier channel **108** in the GaN layer **104** are configured as a transistor. When a voltage is applied to the gate stack, a device current of the transistor could be modulated.

FIG. 2 is a flowchart of a method **200** of forming a semiconductor structure having a HEMT according to one or more embodiments of this disclosure. Referring now to FIG. 2, the flowchart of the method **200**, at operation **201**, a first III-V compound layer is provided. The first III-V compound layer is formed on a substrate. Next, the method **200** continues with operation **202** in which a second III-V compound layer is epitaxially grown on the first III-V compound layer. The method **200** continues with operation **203** in which a source feature and a drain feature are formed on the second III-V compound layer. The method **200** continues with operation **204** in which a gate dielectric layer is deposited on a portion of the second III-V compound layer. The method **200** continues with operation **206** in which a gate electrode is formed on the treated gate dielectric layer between the source feature and the drain feature. It should be noted that additional processes may be provided before, during, or after the method **200** of FIG. 2.

FIGS. 3 to 7 are cross-sectional views of the semiconductor structure **100** having a HEMT at various stages of manufacture according to various embodiments of the method **200** of FIG. 2. Various figures have been simplified for a better understanding of the inventive concepts of the present disclosure.

Referring to FIG. 3, which is an enlarged cross-sectional view of a portion of a substrate **102** of a semiconductor structure **100** after performing operations **201**, **202** and **203**. In some embodiments, the substrate **102** includes a silicon carbide (SiC) substrate, sapphire substrate or a silicon substrate. A first III-V compound layer **104**, also referred to as a channel layer, is grown on the substrate **102**. In the embodiment of FIGS. 2-7, the first III-V compound layer **104** refers to a gallium nitride (GaN) layer (also referred to as the GaN layer **104**). The GaN layer **104** can be epitaxially grown by metal organic vapor phase epitaxy (MOVPE) using gallium-containing precursor and nitrogen-containing precursor. The gallium-containing precursor includes trimethylgallium (TMG), triethylgallium (TEG), or other suitable chemical. The nitrogen-containing precursor includes ammonia (NH<sub>3</sub>), tertiarybutylamine (TBAm), phenyl hydrazine, or other suitable chemical. In the embodiment of FIGS. 2-7, the GaN layer **104** has a thickness in a range from about 0.5 micron to about 10 microns. In other embodiments, the first III-V compound layer **104** may include a GaAs layer or InP layer.



A second III-V compound layer **106**, also referred to as donor-supply layer, is grown on first III-V compound layer **104**. An interface is defined between the first III-V compound layer **104** and the second III-V compound layer **106**. A carrier channel **108** of 2DEG is located at the interface. In at least one embodiment, the second III-V compound layer **106** refers to an aluminum gallium nitride (AlGaN) layer (also referred to as the AlGaN layer **106**). In the embodiment of FIGS. 2-7, the AlGaN layer **106** is epitaxially grown on the GaN layer **104** by MOVPE using aluminum-containing precursor, gallium-containing precursor, and nitrogen-containing precursor. The aluminum-containing precursor includes trimethylaluminum (TMA), triethylaluminum (TEA), or other suitable chemical. The gallium-containing precursor includes TMG, TEG, or other suitable chemical. The nitrogen-containing precursor includes ammonia, TBAm, phenyl hydrazine, or other suitable chemical. In the embodiment of FIGS. 2-7, the AlGaN layer **106** has a thickness in a range from about 5 nanometers to about 50 nanometers. In other embodiments, the second III-V compound layer **106** may include an AlGaAs layer, or AlInP layer.

Further, the second III-V compound layer **106** may include an InGaN diffusion barrier layer **130**. The InGaN diffusion barrier layer **130** may be grown at a range of about 300 mbar to about 500 mbar and in a range of about 700° C. to about 900° C. The Indium composition of the InGaN diffusion barrier layer **130** may be in a range from about 5% to about 10%.

Thereafter, a P-type GaN layer is disposed onto the second III-V compound layer **106**. A patterned mask layer (i.e., a photoresistive layer not shown) is formed on the top surface of the P-type GaN layer and an etching process is performed to remove a portion of the P-type GaN layer. As a result of this lithographic process, a P-type GaN structure **123** is formed.

Next, a dielectric cap layer **110** is deposited on a top surface **107** of the second III-V compound layer **106** and over the top surface of the P-type GaN structure **123**. Therefore, the P-type GaN structure **123** is effectively embedded in the dielectric cap layer **110**. In the embodiment of FIGS. 2-7, the dielectric cap layer **110** has a thickness in a range from about 100 Å to about 5000 Å. In some embodiments, the dielectric cap layer **110** includes SiO<sub>2</sub> or Si<sub>3</sub>N<sub>4</sub>. In one example, the dielectric cap layer **110** is Si<sub>3</sub>N<sub>4</sub> and is formed by performing a low pressure chemical vapor deposition (LPCVD) method without plasma using SiH<sub>4</sub> and NH<sub>3</sub> gases. An operation temperature is in a range of from about 650° C. to about 800° C. An operation pressure is in a range of about 0.1 Torr and about 1 Torr. The dielectric cap layer **110** protects the underlying second III-V compound layer **106** from damage in the following processes having plasma. Next, two openings in the dielectric cap layer **110** are defined by lithography and etching processes to expose a portion of the second III-V compound layer **106**.

A metal layer is deposited over the dielectric cap layer **110**, overfills the openings and contacts the second III-V compound layer **106**. A photoresist layer (not shown) is formed over the metal layer and developed to form a feature over the openings. The metal layer not covered by the feature of the photoresist layer is removed by a reactive ion etch (RIE) process that etches the exposed portions of the metal layer down to the underlying the dielectric cap layer **110**. Metal features **112** are generated after the etching process. The metal features **112** are configured as the source feature or the drain feature for the HEMT. The photoresist layer is removed after the formation of the metal features **112**. The dielectric cap layer **110** protects the underlying second III-V compound layer **106** from damage during the etching process to form

metal features **112**. The carriers in carrier channel **108** of 2DEG underlying the second III-V compound layer **106** would not be affected during the etching process. The electrical performances of the semiconductor structure **100** would be positively affected. Therefore, the yield of the overall assembly could increase.

In some embodiments, the metal layer of the metal features **112** includes one or more conductive materials. In at least one example, the metal layer is free of gold (Au) and comprises titanium (Ti), titanium nitride (TiN), or aluminum copper (AlCu) alloy. In another example, the metal layer includes a bottom Ti/TiN layer, an AlCu layer overlying the bottom Ti/TiN layer, and a top Ti layer overlying the AlCu layer. The formation methods of the metal layer include atomic layer deposition (ALD) or physical vapor deposition (PVD) processes. Without using Au in the metal features **112**, the method **200** could also be implemented in the production line of integrated circuits on silicon substrate. The contamination concern from Au on the silicon fabrication process could be eliminated.

Next, a protection layer (not shown) is optionally deposited on top surfaces of the metal features **112** and the dielectric cap layer **110**. In some embodiments, the protection layer includes dielectric materials such as SiO<sub>2</sub> or Si<sub>3</sub>N<sub>4</sub>. In one example, the protection layer is Si<sub>3</sub>N<sub>4</sub> and is formed by performing a plasma enhanced chemical vapor deposition (PECVD) method.

FIG. 4 illustrates the structure **100** after forming isolation regions **114** in the first III-V compound layer **104** and the second III-V compound layer **106**. The isolation regions **114** isolate the HEMT in the structure **100** from other devices in the substrate **102**. In one example, the isolation region **114** is formed by an implantation process with species of oxygen or nitrogen. The protection layer covers the source feature and the drain feature, and prevents the source feature and the drain feature from exposure during an annealing process after the implantation process for the isolation region **114** formation.

FIG. 5 illustrates the structure **100** after forming an opening **116** in the dielectric cap layer **110** (also in the protection layer if the protection layer exists). A patterned mask layer (not shown) is formed on a top surface of the dielectric cap layer **110** and an etching process is performed to remove a portion of the dielectric cap layer **110** (also remove a portion of the protection layer if the protection layer exists). The opening **116** exposes a portion of the top surface **107** of the second III-V compound layer **106**, and exposes the top surface of P-type GaN structure **123**. In particular, the width of the opening **116** is greater than the width of the P-type GaN structure **123**, so that some portion of the second III-V compound layer **106** is exposed on either side of the P-type GaN structure **123**. The opening **116** is configured as a location for the later gate electrode formation.

FIG. 6 illustrates the structure **100** after depositing a gate dielectric layer **118** in operation **204**. The gate dielectric layer **118** is deposited on the dielectric cap layer **110**, along an interior surface of the opening **116** and on the exposed portion of the second III-V compound layer **106**, and the top surface of the P-type GaN structure **122**. The gate dielectric layer **118** is also deposited over the source feature and the drain feature. In some embodiments, the gate dielectric layer **118** is in a thickness range from about 3 nm to about 20 nm. In some examples, the gate dielectric layer **118** comprises silicon oxide, silicon nitride, gallium oxide, aluminum oxide, scandium oxide, zirconium oxide, lanthanum oxide or hafnium oxide. In one embodiment, the gate dielectric layer **118** is formed by an atomic layer deposition (ALD) method. The ALD method is based on the sequential use of a gas phase

chemical process. The majority of ALD reactions use two chemicals, typically called precursors. These precursors react with a surface one-at-a-time in a sequential manner. By exposing the precursors to the growth surface repeatedly, the gate dielectric layer **118** is deposited. The ALD method provides an uniform thickness of the gate dielectric layer **118** with high quality. In one example, the gate dielectric layer **118** is zirconium oxide. In some embodiments, a first precursor includes tetrakis[ethylmethylamino]zirconium (TEMAZr) or zirconium chloride ( $\text{ZrCl}_4$ ). In some embodiments, a second precursor includes oxygen in order to oxidize the first precursor material to form a monolayer. In some examples, the second precursor includes ozone ( $\text{O}_3$ ), oxygen, water ( $\text{H}_2\text{O}$ ),  $\text{N}_2\text{O}$  or  $\text{H}_2\text{O}-\text{H}_2\text{O}_2$ . In other embodiments, the gate dielectric layer **118** is formed by a plasma enhanced chemical vapor deposition (PECVD) or a low pressure chemical vapor deposition (LPCVD).

FIG. 7 illustrates the structure **100** after performing operation **206**, which forms a gate electrode **128** on the P-type GaN structure **123** of the gate dielectric layer **119**. In one example, a gate electrode layer is deposited on the gate dielectric layer **119** and overfills the opening **116** shown in FIG. 6. Lithography and etching processes are performed on the gate electrode layer to define the gate electrode **128** between the source and drain features. In some embodiments, the gate electrode **128** includes a conductive material layer that includes a refractory metal or its compounds, e.g., titanium (Ti), titanium nitride (TiN), titanium tungsten (TiW) and tungsten (W). In another example, the gate electrode **128** includes nickel (Ni), gold (Au) or copper (Cu).

Various embodiments of the present disclosure may be used to improve the performance of a semiconductor structure having a high electron mobility transistor (HEMT). For example, in conventional methods, a portion of the second III-V compound layer **106** is etched to form a recess for an enhanced-mode HEMT. During etching the recess, the etching uniformity among the semiconductor chip regions on the same substrate **102** is hard to control. The electrical performances of each HEMT in the same semiconductor chip region or the same substrate **102** could not be accurately controlled. In this disclosure, the fluorine region **124** depletes the electrons in the carrier channel **108** for an enhanced-mode HEMT. The fluorine region **124** in the opening **116** eliminates the drawbacks in conventional methods. The fluorine-treated gate dielectric layer **119** also improves stability of the threshold voltage ( $V_t$ ) of the HEMT in the structure **100**. The metal feature **112** is free of Au and comprises Al, Ti or Cu. Without using Au in the metal feature **112**, the method **200** can be implemented in the production line of integrated circuits on silicon substrate, because the contamination concern from Au on the silicon-Fab process is eliminated. Compared with the HEMT with Au in source/drain feature, the cost for manufacturing the HEMT according to the present application is reduced. Both the III-V semiconductor compounds process and the silicon-fabrication process can be implemented in the same production line. It increases the flexibility to allocate different products for the production line.

One aspect of the disclosure describes a semiconductor structure. The semiconductor structure includes a first III-V compound layer. A second III-V compound layer is disposed on the first III-V compound layer and different from the first III-V compound layer in composition. A carrier channel is located between the first III-V compound layer and the second III-V compound layer. A source feature and a drain feature are disposed on the second III-V compound layer. A gate electrode is disposed over the second III-V compound layer between the source feature and the drain feature. A

fluorine region is embedded in the second III-V compound layer under the gate electrode. A gate dielectric layer is disposed over the second III-V compound layer. The gate dielectric layer has a fluorine segment on the fluorine region and under at least a portion of the gate electrode.

A further aspect of the disclosure describes a semiconductor structure. The semiconductor structure includes a GaN layer disposed on a substrate. An AlGaN layer is disposed on the GaN layer. A source feature and a drain feature spaced apart are disposed on the AlGaN layer. A gate electrode is disposed over the AlGaN layer between the source feature and the drain feature. A portion of a gate dielectric layer is disposed between the gate electrode and the AlGaN layer. An InGaN diffusion barrier layer **130** may be disposed on top of the AlGaN layer and beneath an Magnesium doped p-GaN cap layer.

The present disclosure also describes an aspect of a method of forming a semiconductor structure. The method includes providing a first III-V compound layer. A second III-V compound layer is epitaxially grown on the first III-V compound layer. A carrier channel is located between the first III-V compound layer and the second III-V compound layer. A source feature and a drain feature are formed on the second III-V compound layer. A gate dielectric layer is deposited on a portion of the second III-V compound layer. The gate dielectric layer on the portion of the second III-V compound layer is treated with fluorine. A gate electrode is formed on the treated gate dielectric layer between the source feature and the drain feature.

According to an embodiment, a semiconductor structure comprises a first III-V compound layer, and a second III-V compound layer disposed on the first III-V compound layer and different from the first III-V compound layer in composition. The semiconductor structure further comprises a third III-V compound layer disposed over the second III-V compound layer, wherein a diffusion barrier layer is interposed between the second III-V compound layer and the third III-V compound layer, and a source contact and a drain contact disposed on the second III-V compound layer, wherein the third III-V compound layer is interposed between the source contact and the drain contact.

According to another embodiment, a semiconductor structure comprises a first III-V material, and a second III-V material disposed on the first III-V material, the first III-V material and the second III-V material forming an interface therebetween. The semiconductor structure further comprises a source contact and a drain contact disposed on the second III-V material, a gate electrode disposed over the second III-V material between the source contact and the drain contact, and a diffusion barrier layer on a portion of the second III-V material. The semiconductor structure further comprises a third III-V material disposed on the diffusion barrier layer, and a gate dielectric layer disposed over portions of the second III-V material and over a top surface of the third III-V material.

According to yet another embodiment, a method of forming a semiconductor structure, the method comprises forming a second III-V material on a first III-V material, wherein the second III-V material is different from the first III-V material, forming a source contact and a drain contact on the second III-V material, and forming a diffusion barrier layer on the second III-V material. The method further comprises forming a third III-V material on the diffusion barrier layer, depositing a gate dielectric layer on a portion of the second III-V material and a top surface of the third III-V material, and forming a gate electrode between the source contact and the drain contact.

Although the embodiments and its advantages have been described in detail, it should be understood that various changes, substitutions and alterations can be made herein without departing from the spirit and scope of the invention as defined by the appended claims. Moreover, the scope of the present application is not intended to be limited to the particular embodiments of the process, machine, manufacture, and composition of matter, means, methods and steps described in the specification. As one of ordinary skill in the art will readily appreciate from the disclosure of the present invention, processes, machines, manufacture, compositions of matter, means, methods, or steps, presently existing or later to be developed, that perform substantially the same function or achieve substantially the same result as the corresponding embodiments described herein may be utilized according to the present invention. Accordingly, the appended claims are intended to include within their scope such processes, machines, manufacture, compositions of matter, means, methods, or steps.

What is claimed is:

1. A semiconductor structure comprising:
  - a first III-V compound layer;
  - a second III-V compound layer disposed on the first III-V compound layer and different from the first III-V compound layer in composition;
  - a third III-V compound layer disposed over the second III-V compound layer, wherein a diffusion barrier layer is interposed between the second III-V compound layer and the third III-V compound layer; and
  - a source contact and a drain contact disposed on the second III-V compound layer, wherein the third III-V compound layer and the diffusion barrier layer are interposed between the source contact and the drain contact.
2. The semiconductor structure of claim 1, further comprising a gate electrode disposed over the third III-V compound layer.
3. The semiconductor structure of claim 2, wherein a width of the third III-V compound layer is less than a width of the gate electrode.
4. The semiconductor structure of claim 2, further comprising a gate dielectric layer, the gate dielectric layer being interposed between the gate electrode and the second III-V compound layer.
5. The semiconductor structure of claim 1, wherein a channel is located at an interface between the first III-V compound layer and the second III-V compound layer.
6. The semiconductor structure of claim 5, wherein the channel is a two-dimensional electron gas.
7. The semiconductor structure of claim 1, further comprising a dielectric cap layer disposed over the second III-V compound layer, the source contact and the drain contact extending through the dielectric cap layer.
8. A semiconductor structure comprising:
  - a first III-V material;
  - a second III-V material disposed on the first III-V material, the first III-V material and the second III-V material forming an interface therebetween;
  - a source contact and a drain contact disposed on the second III-V material;

- a gate electrode disposed over the second III-V material between the source contact and the drain contact;
  - a diffusion barrier layer on a portion of the second III-V material;
  - a third III-V material disposed on the diffusion barrier layer; and
  - a gate dielectric layer disposed over portions of the second III-V material and over a top surface of the third III-V material, wherein the gate dielectric layer is disposed over the source contact and the drain contact.
9. The semiconductor structure of claim 8, further comprising a dielectric cap layer, the dielectric cap layer being interposed between the gate dielectric layer and the second III-V material.
  10. The semiconductor structure of claim 9, wherein the dielectric cap layer has a thickness between about 100 Å and about 5000 Å.
  11. The semiconductor structure of claim 8, wherein a channel is located at the interface between the first III-V material and the second III-V material.
  12. The semiconductor structure of claim 11, wherein the channel is a two-dimensional electron gas.
  13. The semiconductor structure of claim 8, wherein a width of the diffusion barrier layer is less than a width of the gate electrode.
  14. The semiconductor structure of claim 8, wherein a width of the diffusion barrier layer is less than a width of the second III-V material.
  15. A method of forming a semiconductor structure, the method comprising:
    - forming a second III-V material on a first III-V material, wherein the second III-V material is different from the first III-V material;
    - forming a source contact and a drain contact on the second III-V material;
    - forming a diffusion barrier layer on the second III-V material;
    - forming a third III-V material on the diffusion barrier layer;
    - depositing a gate dielectric layer on a portion of the second III-V material and a top surface of the third III-V material; and
    - forming a gate electrode between the source contact and the drain contact, at least a portion of the gate electrode extending along a sidewall of the third III-V material.
  16. The method of claim 15, wherein the forming the third III-V material comprises doping the third III-V material.
  17. The method of claim 15, further comprising forming a dielectric cap layer on the second III-V material, the diffusion barrier layer being disposed in an opening in the dielectric cap layer.
  18. The method of claim 15, wherein a width of the diffusion barrier layer is substantially equal to a width of the third III-V material.
  19. The method of claim 15, wherein the forming the second III-V material comprises epitaxially growing the second III-V material on the first III-V material.
  20. The method of claim 15, wherein a two-dimensional electron gas is formed at an interface between the first material III-V material and the second III-V material.

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